

# LNJ814R88RA

## High Bright Surface Mounting Chip LED

TSS Type

### Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	50	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

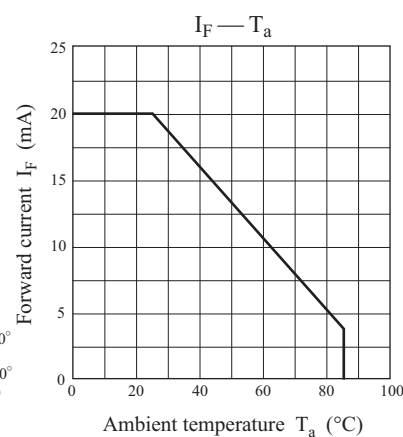
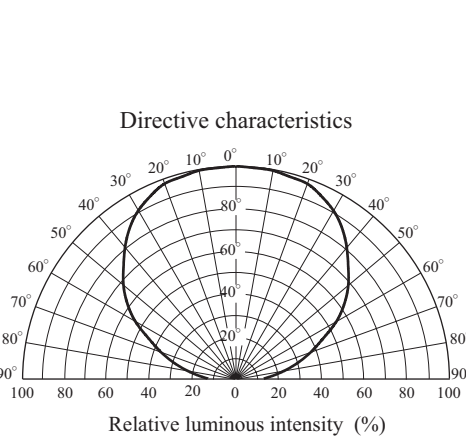
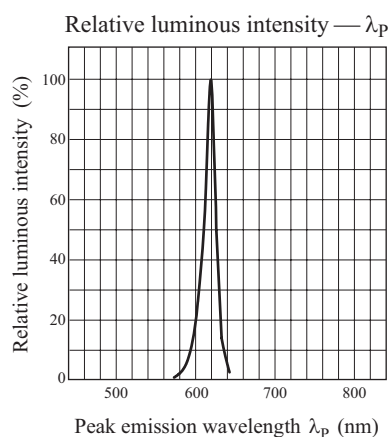
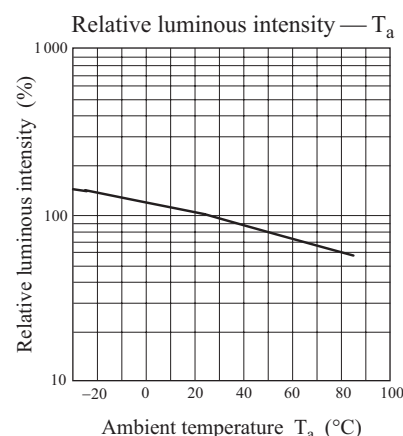
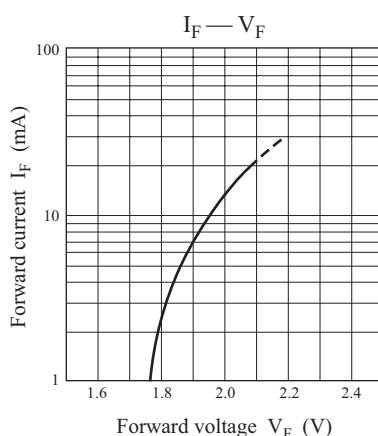
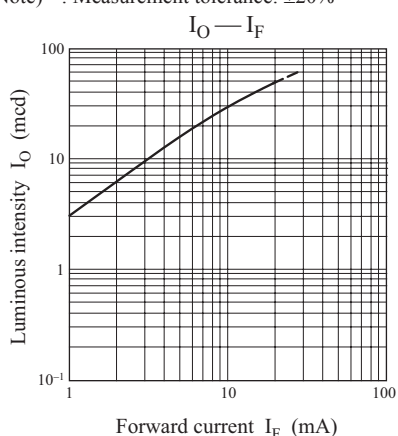
### Lighting Color

- Orange

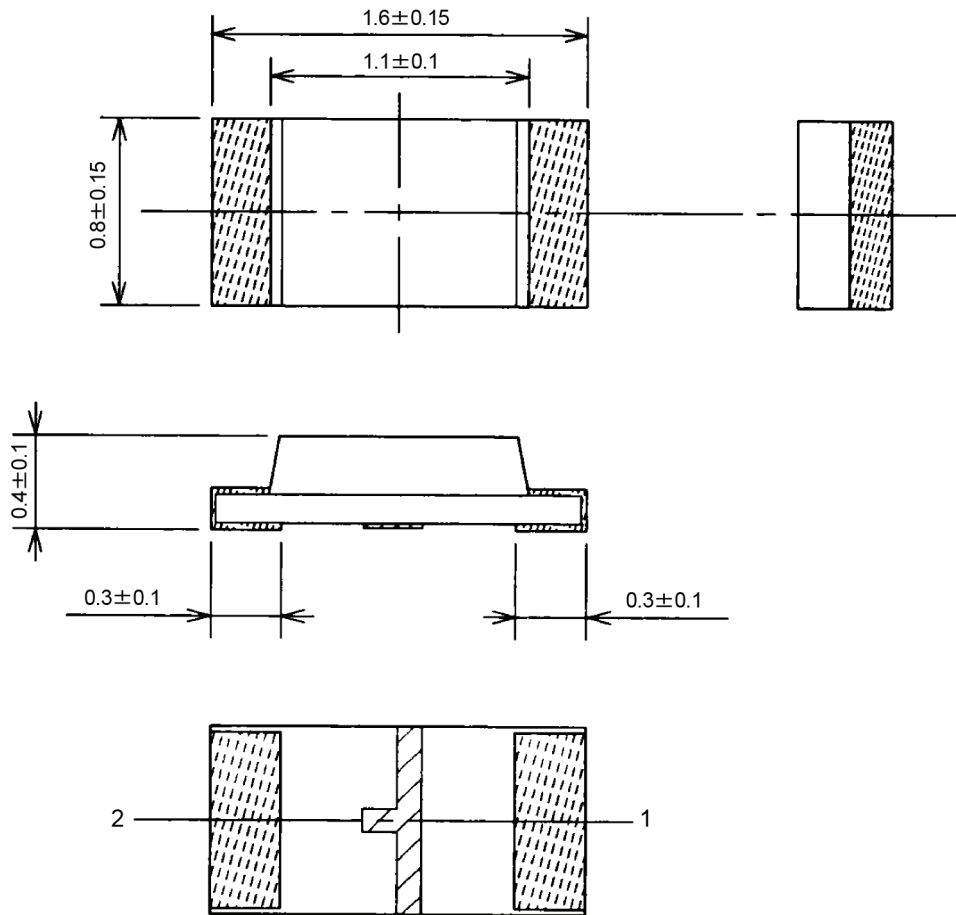
### Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	$I_O$	$I_F = 10\text{ mA}$	16	30		mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.95	2.50	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		620		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		17		nm

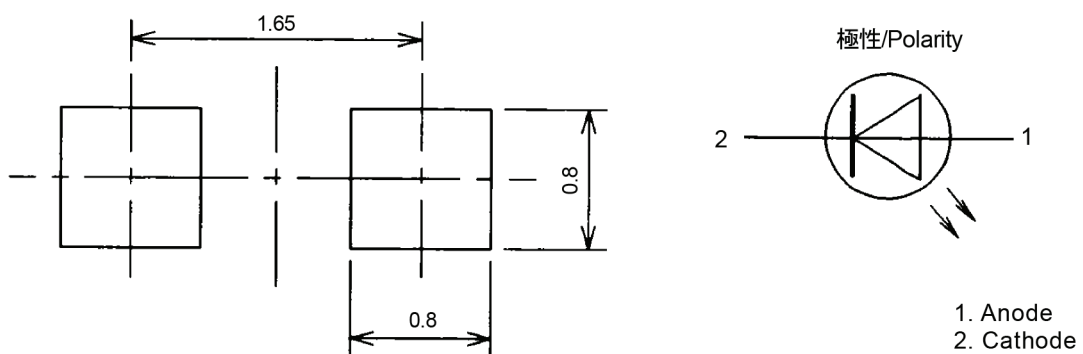
Note) \*: Measurement tolerance:  $\pm 20\%$



■ Package (Unit: mm)



〈推奨パターン/Recommended land layout〉



(注 1) パッケージ寸法については電極バリを含まない。  
(Note1) Electrode projection is not included in the package dimensions.

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